



US 20240213235A1

(19) **United States**

(12) **Patent Application Publication**
Nad et al.

(10) **Pub. No.: US 2024/0213235 A1**

(43) **Pub. Date: Jun. 27, 2024**

(54) **ARCHITECTURES FOR BACKSIDE POWER DELIVERY WITH STACKED INTEGRATED CIRCUIT DEVICES**

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(21) Appl. No.: **18/089,459**

(22) Filed: **Dec. 27, 2022**

Publication Classification

(51) **Int. Cl.**
H01L 25/18 (2006.01)
H01L 23/00 (2006.01)
H01L 25/00 (2006.01)
H01L 25/065 (2006.01)

(52) **U.S. Cl.**

CPC **H01L 25/18** (2013.01); **H01L 24/08** (2013.01); **H01L 24/80** (2013.01); **H01L 25/0657** (2013.01); **H01L 25/50** (2013.01); **H01L 2224/08145** (2013.01); **H01L 2224/80895** (2013.01); **H01L 2224/80896** (2013.01); **H01L 2225/06548** (2013.01); **H01L 2225/06586** (2013.01); **H01L 2225/06589** (2013.01); **H01L 2924/1427** (2013.01); **H01L 2924/1431** (2013.01)

(57)

ABSTRACT

An apparatus is provided which comprises: an integrated circuit logic device, an integrated circuit power device conductively coupled with a first surface of the integrated circuit logic device, wherein the integrated circuit power device extends laterally beyond a side of the integrated circuit logic device, one or more vias adjacent the side of the integrated circuit logic device extending from contact with the integrated circuit power device to level with a second surface of the integrated circuit logic device opposite the first surface of the integrated circuit logic device, and conductive contacts on the second surface of the integrated circuit logic device. Other embodiments are also disclosed and claimed.

